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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10008704	FILING DATE 12/06/2001	CLASS 257 138	SUBCLASS 678	GAU 2825 2812	EXAMINER Tran, Tan
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**APPLICANTS: Ahn Sang-Ho; Oh Se-Ycng;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

REPUBLIC OF KOREA 2001-11182 03/05/2001

REPUBLIC OF KOREA 2001-38717 06/30/2001

PG-PUB DO NOT PUBLISH <input type="checkbox"/>	RESUME <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed 33 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	9903-045
Verified and Acknowledged Examiner's initials		
TITLE: Ultra-thin semiconductor package device and method for manufacturing the same U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		Application Examiner
		PREPARED FOR ISSUE		
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